



RELIABILITY REPORT  
FOR  
MAX13362ATL+  
PLASTIC ENCAPSULATED DEVICES

September 29, 2009

**MAXIM INTEGRATED PRODUCTS**

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## Conclusion

The MAX13362ATL+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX13362 is a 24-channel automotive contact monitor designed as an interface between mechanical switches and low-voltage processors or other logic circuits. The IC operates over a voltage range of 5.5V to 28V, and withstands voltages up to 40V. It protects low-voltage circuitry from high voltages and reverse battery conditions. The MAX13362's low-current operation under all operating conditions makes it suitable for use in electronic control units (ECUs) that are connected directly to the automotive battery. It has an adjustable scan mode that significantly reduces the current drawn in key-off.

The MAX13362 features an SPI™ interface to monitor the switch status and set the device configuration. Multiple MAX13362s can be cascaded to support any multiple of 24 switches.

The MAX13362 is available in a 6mm x 6mm, 40-pin thin QFN package and operates over the -40°C to +125°C temperature range.

An evaluation kit is available: MAX13362EVKIT



## II. Manufacturing Information

A. Description/Function:	Monitor the Status of 24 Automotive Switches with a Single Microcontroller
B. Process:	S45
C. Number of Device Transistors:	28989
D. Fabrication Location:	California, Texas or Japan
E. Assembly Location:	China Thailand
F. Date of Initial Production:	1/23/2009

## III. Packaging Information

A. Package Type:	40-pin TQFN 6x6
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3078
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	38°C/W
K. Single Layer Theta Jc:	1.4°C/W
L. Multi Layer Theta Ja:	27°C/W
M. Multi Layer Theta Jc:	1.4°C/W

## IV. Die Information

A. Dimensions:	144 X 134 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw



## V. Quality Assurance Information

- |                                   |   |
|-----------------------------------|---|
| A. Quality Assurance Contacts:    | Ken Wendel (Director, Reliability Engineering)<br>Bryan Preeshl (Managing Director of QA)       |
| B. Outgoing Inspection Level:     | 0.1% for all electrical parameters guaranteed by the Datasheet.<br>0.1% For all Visual Defects. |
| C. Observed Outgoing Defect Rate: | < 50 ppm  |
| D. Sampling Plan:                 | Mil-Std-105D  |

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = x \times 10^{-9}$$

$\lambda$  = F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the S45 Process results in a FIT Rate of 0.49 @ 25C and 8.49 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The AB01 die type has been found to have all pins able to withstand an ESD transient pulse of:

HBM: +/-2000 V per JESD22 - A114  
CDM: +/-750 V per JESD22 - C101

Latch-Up testing has shown that this device withstands a current of +/-100 mA, 1.5x VCCMax Overvoltage per JESD78.



**Table 1**  
Reliability Evaluation Test Results

**MAX13362ATL+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	0	0
<b>Moisture Testing</b> (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data